

Zynq UltraScale+ MPSoC

OVERVIEW

Zynq® UltraScale+™ MPSoCs combine a high-performance Arm®-based multicore, multiprocessing system with ASIC-class programmable logic. These devices, equipped with dual- and quad-core application processors, deliver maximum scalability and are capable of offloading critical applications, such as graphics and video pipelining, to dedicated processing blocks, along with a full complement of integrated peripherals and connectivity cores suitable for next-generation systems.

Fully integrated programmable logic enables custom co-processors and custom memory hierarchies to meet application specific needs, including deep learning processing units (DPU) for AI/ML processing. The 16nm FinFET+ programmable logic communicates with the processing system through 6,000 interconnects, enabling bandwidth that is not possible with multichip solutions. Dramatic power savings are achieved through fine-grained control of power domains and gated power islands. With specialized processing elements for different workloads, Zynq UltraScale+ MPSoCs are optimal single-chip platforms for both cost-sensitive and high-performance applications.

HIGHLIGHTS

New ZU1 Device: Lowest-Cost, Lowest Power Entry Point

- > Same Arm Multiprocessing subsystem for portfolio scalability
- > 40% less static power than ZU2 device, with only 20% less programmable logic
- > Highest I/O-to-System Logic Cell ratio to maximize connectivity
- > Highest DSP-to-System Logic Cell ratio for maximum compute and AI offloading

Packaging Innovation for Industry's Highest Compute Density

- > Integrated Fan-Out (InFO) packaging for ultra-compact form factor (9.5x15mm)
- > 60% less area (than flip-chip packaging) for better thermal & power distribution
- > 5X compute density vs comparable ASSPs (DMIPS/mm²)
- > Available for ZU1, ZU2, and ZU3 devices

Architectural Advantages vs. ASSPs

- > Custom memory hierarchy for highest throughput, lowest latency designs
- > Tightly coupled memory enables full isolation of safety critical functions
- > Soft co-processors for offloading or extra processing capability
- > AI/ML processing capable with custom deep learning processing units (DPU)
- > Scalable with the full Zynq MPSoC portfolio – preserve your design investment



TARGET APPLICATIONS

Industrial

- > Machine Vision
- > Industrial Networking (Time-Sensitive Networking)
- > Industrial Controllers
- > Retail Analytics
- > Robotics
- > Drives

Medical

- > Portable and Desktop Ultrasound
- > External Defibrillators
- > Endoscopy

Automotive

- > Monitoring Systems
- > Front Camera Drivers Assist Systems

AV Broadcasting

- > Portable Pico Projectors
- > Small Form Factor Broadcast

Aerospace & Defense

- > MILCOM Radio
- > Missiles & Munitions

FEATURES

	CG Devices	EG Devices	EV Devices
PROCESSING SYSTEM			
Application Processing Unit	Dual-core Arm® Cortex®-A53	Quad-core Arm Cortex-A53	Quad-core Arm Cortex-A53
Real-Time Processing Unit	Dual-core Arm Cortex-R5F	Dual-core Arm Cortex-R5F	Dual-core Arm Cortex-R5F
Graphics Processing Unit	–	Arm Mali™-400 MP2	Arm Mali-400 MP2
Video Codec Unit	–	–	Up to 8K @ 15fps Supports H.264/H.265
Embedded and External Memory	256KB On-Chip Memory w/ECC; External DDR4/3/3L; LPDDR4/3; External Quad-SPI; NAND; eMMC		
PROGRAMMABLE LOGIC*			
System Logic Cells (K)	600	1,143	504
DSP Slices	2,520	3,528	1,728
Transceivers	24 @ 16Gb/s	44 @ 16Gb/s 28 @ 32Gb/s	24 @ 16Gb/s
On-Chip Memory (Mb)	44.2	80.4	44.2
PCIe® Gen3 x16	2	5	2
100G Ethernet Blocks with RS-FEC	–	4	–
150G Interlaken	–	4	–
FEATURES OVERVIEW			
Dynamic Power Management	<ul style="list-style-type: none"> > Multiple power domains with granular gating control > Platform Management Unit for power, safety, and reliability 		
Safety and Security	<ul style="list-style-type: none"> > Configuration Security Unit for anti-tamper and lockdown > Support for 4096-bit RSA keys with SHA-3 hash functions > Secure system boot with AES 256 decryption > Full Arm TrustZone support 		
Custom Memory Hierarchy	<ul style="list-style-type: none"> > Up to 10MB of internal local memory for co-processors and custom accelerators > Multiple DDR controller capable for lowest latency memory access > Tightly coupled memory enables isolated design flows for safety-critical applications 		
Deep Learning Processing Unit (DPU) Compatible	<ul style="list-style-type: none"> > Configurable computation engine dedicated to convolutional neural networks > Accelerate AI/ML functions easily with reference designs and pre-built AI models 		

*Maximum for each device family

TAKE THE NEXT STEP

Zynq UltraScale+ MPSoCs are supported by comprehensive development tools, reference designs, an IP catalog, and evaluation platforms. For more information about Xilinx Zynq UltraScale+ MPSoCs, visit <https://www.xilinx.com/zynq-ultrascale-plus.html>. Evaluation kits sold separately; see the [Zynq UltraScale+ MPSoC Kit Selection Guide](#) for details and place an order today.

Corporate Headquarters
Xilinx, Inc.
2100 Logic Drive
San Jose, CA 95124
USA
Tel: 408-559-7778
www.xilinx.com

Xilinx Europe
Xilinx Europe
Bianconi Avenue
Citywest Business Campus
Saggart, County Dublin
Ireland
Tel: +353-1-464-0311
www.xilinx.com

Japan
Xilinx K.K.
Art Village Osaki Central Tower 4F
1-2-2 Osaki, Shinagawa-ku
Tokyo 141-0032 Japan
Tel: +81-3-6744-7777
japan.xilinx.com

Asia Pacific Pte. Ltd.
Xilinx, Asia Pacific
5 Changi Business Park
Singapore 486040
Tel: +65-6407-3000
www.xilinx.com

India
Xilinx India Technology Services Pvt. Ltd.
Block A, B, C, 8th & 13th floors,
Meenakshi Tech Park, Survey No. 39
Gachibowli(V), Seri Lingampally (M),
Hyderabad -500 084
Tel: +91-40-6721-4747
www.xilinx.com



© Copyright 2021 Xilinx, Inc. Xilinx, the Xilinx logo, Artix, ISE, Kintex, Spartan, Virtex, Vivado, Zynq, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. AMBA, AMBA Designer, ARM, ARM1176JZ-S, CoreSight, Cortex, and PrimeCell are trademarks of ARM in the EU and other countries. PCIe, and PCI Express are trademarks of PCI-SIG and used under license. All other trademarks are the property of their respective owners.
Printed in the U.S.A. AC0521